Material Content Data Sheet for EP-type							
Date	2025.10.24			RoHS compliant		YES	
Revision	1.0						
Construction element	Material group	Materials	CAS-Nr. If applicable	Average mass [%] *	Sum [%]	Traces	Comment
Chip	Inorganic material	silicon	7440-21-3	0.3	0.3		
Base plate and substrate including metallization	Non noble metal	copper	7440-50-8	69.3	72.5		
	Inorganic material	Aluminum oxide	1344-28-1	1.9			
	Non noble metal	tin	7440-31-5	1.2			
	Noble metal	silver	7440-22-4			X	
	Non noble metal	nickel	7440-02-0	0.1			
wire	Non noble metal	aluminum	7429-90-5	0.3	0.3		
encapsulation	polymers	Silicone gel		11.1	11.1		
housing	polymers	PBT		9.2	13.2		
	Inorganic material	Glas fiber		4			
lead, finish and plating	Non noble metal	copper	7440-50-8	2.45	2.6		
	Non noble metal	tin	7440-31-5			X	
	Non noble metal	aluminum	7429-90-5	0.05			
	Non noble metal	nickel	7440-02-0			X	
SMD (thermistors)	Inorganic material					X	RoHS compliant
				Sum in total	100		

Weight range of product	300g
Fluctuation margin	< 10%

REMARKS

- The information provided is the full declaration of all materials present in SwissSEM product of EP-type product family above a threshold of 0.1% or 1000 ppm.
- All information is according to the best of our knowledge and subject to change at any time for required changes.
- SwissSEM products are not classified as “hazardous substances” according to the definition of EU directive 67/548/EC and do hence not require a Material Safety Datasheet.